Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-09-04
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Andrea Casali	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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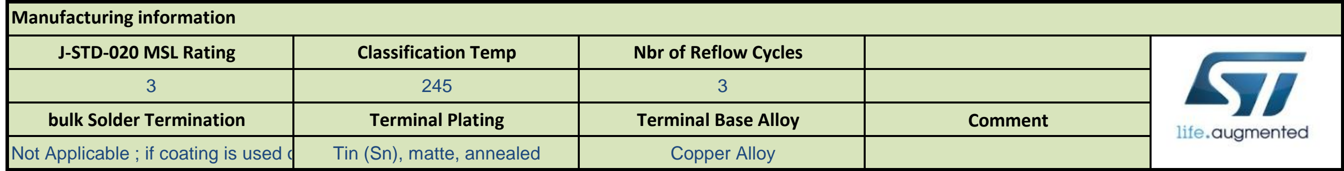
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
TDA7577BLVPDTR	H9ZS*UK78BB6	A	MU1A	2013-09-04
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	1925.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	245	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used c	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	15.75x15.9x3.45	36	flat	
Comment				

Material Composition Declaration						Mfr Item Name	H9ZS*UK78BB6					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	19.53	mg	supplier	die	Silicon (Si)	7440-21-3		18.671	mg	956016	9699
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.123	mg	6298	64
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.123	mg	6298	64
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.149	mg	7629	77
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.03	mg	1536	16
die (s)				supplier	passivation	Indium Tin oxide (In203:SnO2)	50926-11-9		0.288	mg	14747	150
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.011	mg	563	6
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.028	mg	1434	15
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.095	mg	4864	49
die (s)				supplier	polymer die coating	0	Glass: Silicon Dioxide		0.012	mg	614	6
Leadframe	Copper & its alloys	1268.074	mg	supplier	alloy	Copper (Cu)	7440-50-8		1263.148	mg	996115	656181
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.582	mg	459	302
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.062	mg	837	552
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.282	mg	2588	1705
Die attach		11.491	mg	JIG R	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high mel	11.204	mg	975024	5820
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.172	mg	14968	89
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.115	mg	10008	60
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		2.713	mg	1000000	1409
encapsulation		617.735	mg	supplier	mold compound	Phenol Resin	205830-20-2		24.709	mg	39999	12836
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		18.532	mg	30000	9627
encapsulation				supplier	mold compound	epoxy resin	Proprietary		18.532	mg	30000	9627
encapsulation				supplier	mold compound	carbon black	1333-86-4		1.236	mg	2001	642
encapsulation				supplier	mold compound	silica vitreous	60676-86-0		554.726	mg	898000	288169
connections coating	Solder	5.458	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.458	mg	1000000	2835